**Technical Data Sheet**

**ASSEMBLY MATERIALS**

**Product Type:** Non Conductive Adhesive  
**Product Name:** NCA 9-9280

### Description

NCA 9-9280 is a fast curing thermosetting, one-component, solvent-free, high flexible non-conductive adhesive epoxy, designed for the connection of bare dies and SMT components on lead frames, foils and low cost substrates at low temperatures.

### Key Benefits

- Low temperature curing
- High volume production possible
- Snap curing system

### Compliant Products

- Conductive Adhesive: PC3200 and PC3600 Series
- Non-conductive Adhesive: NCA 5, NCA 6, NCA 11

### Applications

- Dispensing

### Physical Properties

<table>
<thead>
<tr>
<th>Pot Life (day)</th>
<th>Curing Profile</th>
<th>Substrate and Components</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>5 min / 90 °C</td>
<td>Flex PCB, flex lead frames, foils and temp-sensitive substrates. Solder resist, Ni/Au and Ag</td>
</tr>
<tr>
<td></td>
<td>15 min / 80 °C</td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Adhesion (N/mm²)</th>
<th>Weight Loss during Curing Process at 150 °C (%)</th>
<th>Glass Transition Temperature (°C)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Max. 20</td>
<td>Max. 0.9</td>
<td>Approx. 29</td>
</tr>
</tbody>
</table>

**Cleaning Instructions**

The uncured adhesive can be removed with Zestron HC and other Zestron and Vigon cleaning materials. The cleaned parts must be completely dry before installing them in the machine. Defective components can be removed by heating the cured adhesive joint with hot air above 250°C. The hot remaining adhesive can be removed with a sharp tool.

### Adhesive Conditioning

- Remove adhesive from freezer: Before opening the package leave it for at least 2 hours at room temperature so that adhesive heats up
- Do not open jar/cartridge while adhesive is cold to prevent condensation
- Do not use faster defrost systems
Storage

- Store the adhesive in tightly-sealed containers and avoid exposure to high humidity and sunlight
- Store the cartridges with tip pointing downwards
- In cartridges: From the date of manufacture 12 months in a freezer at – 20 °C

The descriptions and engineering data shown here have been compiled by Heraeus using commonly accepted procedures, in conjunction with modern testing equipment, and have been compiled as according to the latest factual knowledge in our possession. The information was up to date on the date this document was printed (latest versions can always be supplied upon request). Although the data is considered accurate, we cannot guarantee accuracy, the results obtained from its use, or any patent infringement resulting from its use (unless this is contractually and explicitly agreed in writing, in advance). The data is supplied on the condition that the user shall conduct tests to determine materials suitability for particular applications.